

ABSTRACT OF THE DISCLOSURE

A frame F for semiconductor package has die-pads 3 supported with suspending leads 2 of individual lead frames 10. Semiconductor devices are mounted on die-pads 3. These semiconductor devices are collectively molded with molding compounds, and then the collectively molded semiconductor packages are cut into individual packages by means of dicing saw. In the frame F, thin parts are formed in areas corresponding to neighborhood of the roots of individual terminals, the thin parts being formed by half-cutting by etching metal of the areas from the front or back thereof. Or, hollows are formed in areas corresponding to neighborhood of the roots of individual terminals, Accordingly, it is inhibited that increased sectional area of terminals is formed, so that intervals between adjacent terminals 5 are sufficiently kept. Accordingly, accidents such as soldered bridge do not occur.